

PROPOSED AMENDMENTS TO THE CLAIMS

- (1) Claim 20 would be amended to include the subject matter of claim 25. **BERMAN** does not disclose that both of the dressing units are of a material that is different than that of the workpiece, and discloses that the pre-conditioning head 130 (i.e. one of the dressing units) is of the same material as that of the workpiece as explained in column 7, lines 49-57.
- (2) Claims 25, 30 and 31 would be canceled.
- (3) Claim 32 would be amended to recite that the contact surfaces of each of the first and second dressers comprise diamond particles. In **BERMAN**, while conditioning head 128 is of a diamond grit conditioning head 130 is not.
- (4) Claim 34 would be amended to recite that the dresser to perform the initial surface conditioning is a diamond dresser that thinly shaves the polishing surface. In **BERMAN**, conditioning head 128, which performs an initial surface conditioning, is not a diamond dresser and does not thinly shave the polishing surface.
- (5) Claims 37, 42 and 43 would be rewritten in independent form.
- (6) Claim 44 would be amended so as to define around **BERMAN**, because conditioning head 128 is not to perform a dressing operation after a plurality of wafers has been polished, and pre-conditioning head is not for dressing the polishing surface each time the wafer has been polished.

A copy of the proposed amended claims 20, 32, 34 and 44 is attached.

PROPOSED AMENDMENTS**U.S. Serial No. 09/787,121**

20 (Currently amended) A polishing apparatus comprising:

a polishing table having a polishing surface;

a top ring for pressing a workpiece against said polishing surface ~~at a predetermined pressure~~ so as to polish the workpiece; and

at least two dressing units for dressing said polishing surface by being brought into contact with said polishing surface,

wherein said at least two dressing units are to dress said polishing surface at different times, respectively, and are of a material that is different than that of the workpiece.

32. (Currently amended) A polishing apparatus for polishing a workpiece, comprising:

a table for providing a polishing surface;

a first dresser having a contact surface comprising diamond particles for contacting said polishing surface during a first dressing operation;

a second dresser having a contact surface comprising diamond particles for contacting said polishing surface during a second dressing operation; and

an atomizer for spraying a fluid on said polishing surface to remove a polishing waste present on said polishing surface,

wherein said first dresser and said second dresser are to perform said first dressing operation and said second operation at different times, respectively.

34. (Currently amended) A polishing apparatus comprising:

a polishing table having a polishing surface;

a top ring for pressing a workpiece against said polishing surface ~~at a predetermined pressure~~ so as to polishing the workpiece; and

at least two dressers for dressing said polishing surface,

wherein one of said at least two dressers ~~is~~ comprises a diamond dresser to perform an initial surface conditioning of said polishing surface at a time prior to polishing of any workpiece so as to thinly shave said polishing surface, and another of said at least two dressers is for dressing said polishing surface after the workpiece has been polished.

44.

~~said one of said at least two dressers is to dress said polishing surface after a plurality of workpieces has been polished~~ A polishing apparatus comprising:

a polishing table having a polishing surface;

a top ring for pressing a workpiece against said polishing surface so as to polishing the workpiece; and

at least two dressers for dressing said polishing surface.

wherein one of said at least two dressers comprises a diamond dresser to perform a dressing operation after a plurality of workpieces has been polished, and another of said at least two dressers is for dressing said polishing surface each time the workpiece has been polished.